

Product Summary

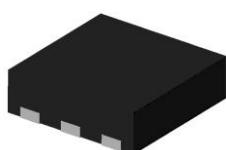
BV_{DSS}	$R_{DS(ON)} \text{ Max}$	$I_D \text{ Max}$ $T_A = +25^\circ\text{C}$
40V	9.5m Ω @ $V_{GS} = 10\text{V}$	11.8A
	15.5m Ω @ $V_{GS} = 4.5\text{V}$	9.2A

Description

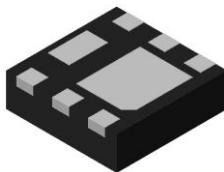
This MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Power Management Functions
- DC-DC Converters
- Backlighting

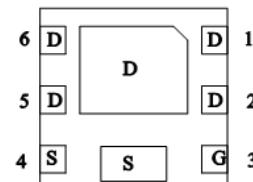
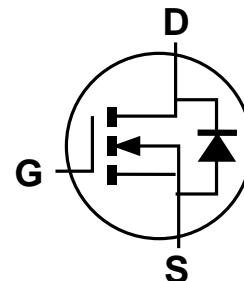


Top View



Bottom View

U-DFN2020-6 (Type F)


 Pin Out
Bottom View


Internal Schematic

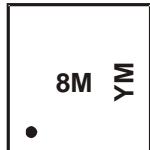
Ordering Information (Note 4)

Part Number	Case	Quantity per Reel
DMT4008LFDF-7	U-DFN2020-6 (Type F)	3,000
DMT4008LFDF-13	U-DFN2020-6 (Type F)	10,000

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



8M = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: F = 2018)
 M = Month (ex: 9 = September)

Date Code Key

Year	2016	2017	2018	2019	2020	2021	2022	2023				
Code	D	E	F	G	H	I	J	K				
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	40	V	
Gate-Source Voltage	V_{GSS}	± 20	V	
Continuous Drain Current (Note 6) $V_{GS} = 10\text{V}$	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	I_D	11.8 9.4	A
Pulsed Drain Current (10 μs Pulse, Duty Cycle = 1%)	I_{DM}	70	A	
Pulsed Body Diode Forward Current (10 μs Pulse, Duty Cycle = 1%)	I_{SM}	70	A	
Continuous Source-Drain Diode Current	I_S	2.2	A	
Avalanche Current, $L = 0.3\text{mH}$	I_{AS}	13.3	A	
Avalanche Energy, $L = 0.3\text{mH}$	E_{AS}	26.5	mJ	

Thermal Characteristics

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	$T_A = +25^\circ\text{C}$	P_D	0.8	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	155	$^\circ\text{C}/\text{W}$	
Total Power Dissipation (Note 6)	$T_A = +25^\circ\text{C}$	P_D	2.0	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	63	$^\circ\text{C}/\text{W}$	
Thermal Resistance, Junction to Case (Note 6)	$T_C = +25^\circ\text{C}$	$R_{\theta JC}$	8.9	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$	

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	40	—	—	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current ($T_J = +25^\circ\text{C}$)	I_{DSS}	—	—	1	μA	$V_{DS} = 32\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(\text{TH})}$	1	1.7	3	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	—	7.8	9.5	$\text{m}\Omega$	$V_{GS} = 10\text{V}, I_D = 10\text{A}$
		—	10.6	15.5		$V_{GS} = 4.5\text{V}, I_D = 8.5\text{A}$
Diode Forward Voltage	V_{SD}	—	0.7	1.0	V	$V_{GS} = 0\text{V}, I_S = 10\text{A}$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	1179	—	pF	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Output Capacitance	C_{oss}	—	384	—		
Reverse Transfer Capacitance	C_{rss}	—	42	—		
Gate Resistance	R_G	—	1.7	—	Ω	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Total Gate Charge ($V_{GS} = 4.5\text{V}$)	Q_G	—	8.3	—	nC	$V_{DD} = 20\text{V}, I_D = 10\text{A}$
Total Gate Charge ($V_{GS} = 10\text{V}$)	Q_G	—	17.1	—		
Gate-Source Charge	Q_{GS}	—	2.4	—		
Gate-Drain Charge	Q_{GD}	—	3.4	—	ns	$V_{DD} = 20\text{V}, V_{GS} = 10\text{V}, R_G = 6\Omega, I_D = 10\text{A}$
Turn-On Delay Time	$t_{D(\text{ON})}$	—	3.5	—		
Turn-On Rise Time	t_R	—	3.7	—		
Turn-Off Delay Time	$t_{D(\text{OFF})}$	—	17.1	—		
Turn-Off Fall Time	t_F	—	6.4	—		
Reverse Recovery Time	t_{RR}	—	19.8	—	ns	$I_F = 10\text{A}, di/dt = 100\text{A}/\mu\text{s}$
Reverse Recovery Charge	Q_{RR}	—	8.8	—	nC	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

7. Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to product testing.

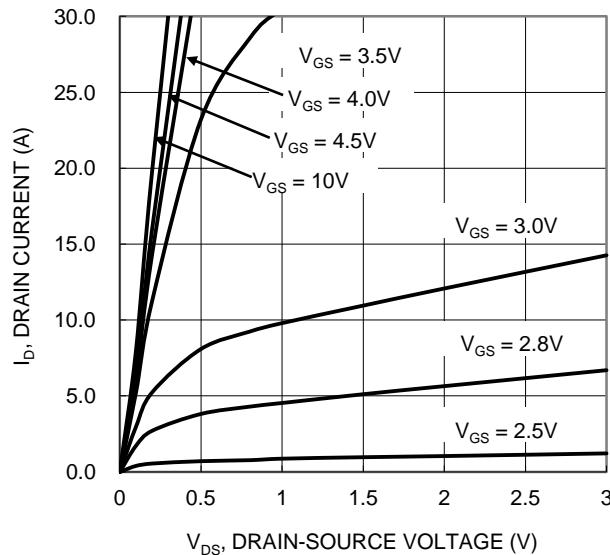


Figure 1. Typical Output Characteristic

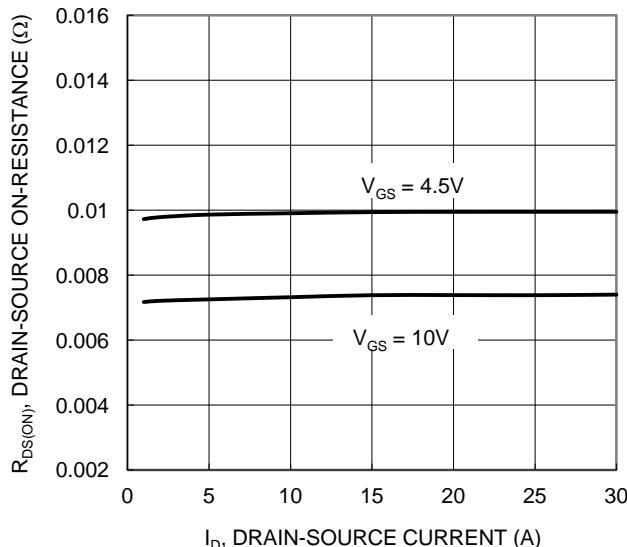


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

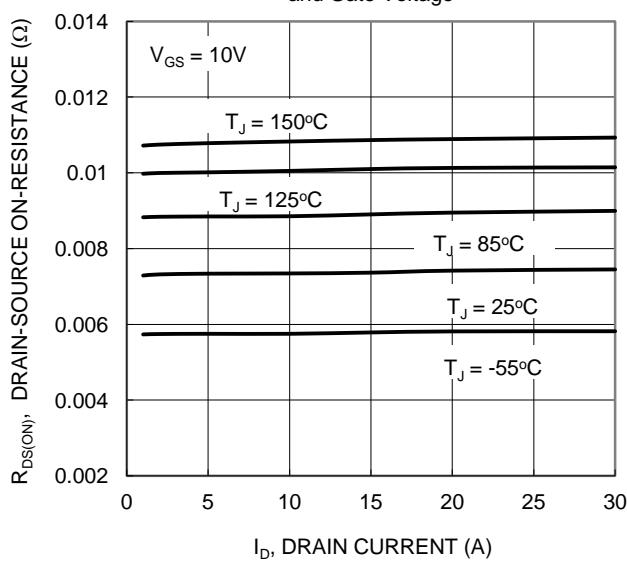


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

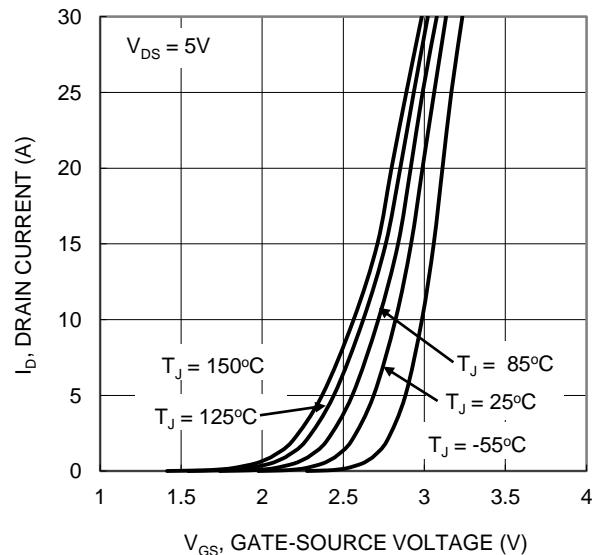


Figure 2. Typical Transfer Characteristic

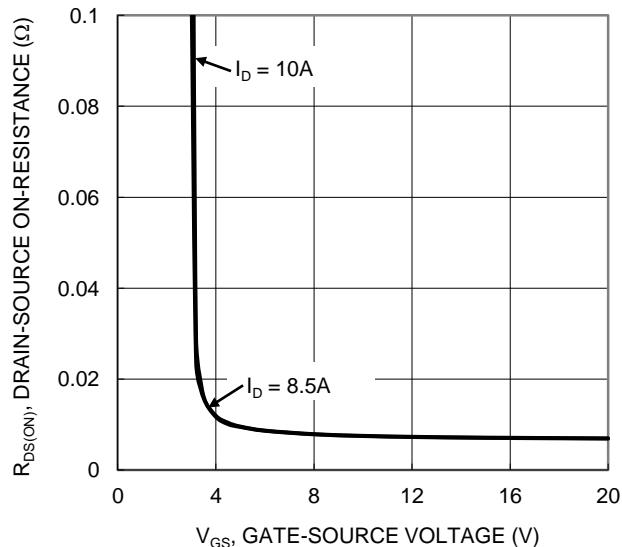


Figure 4. Typical Transfer Characteristic

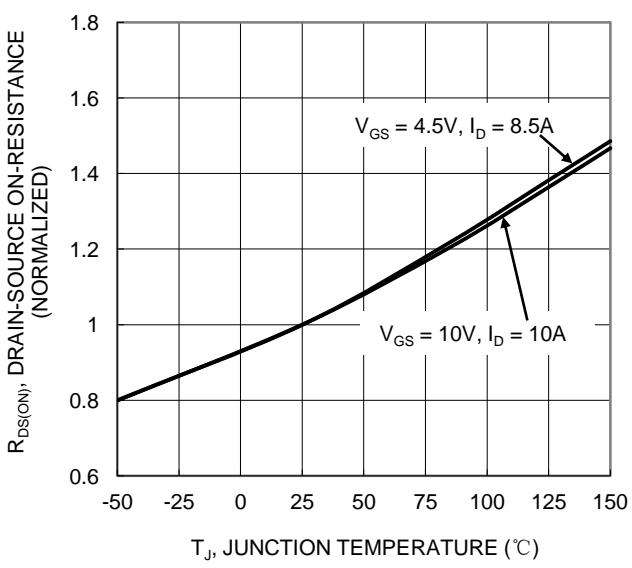
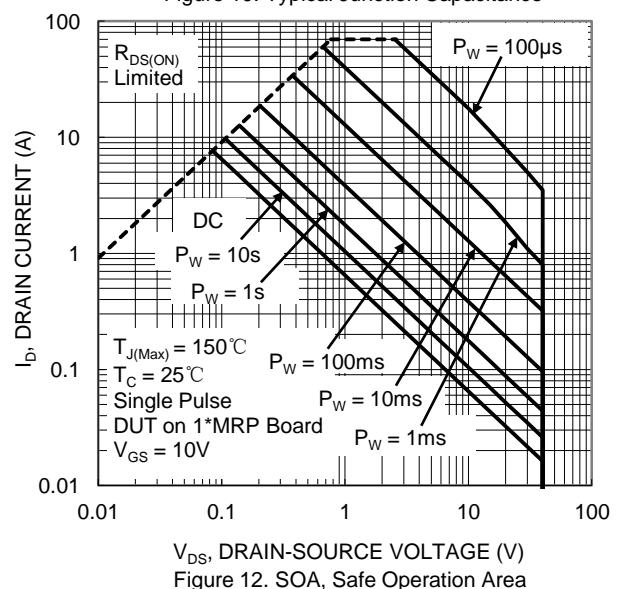
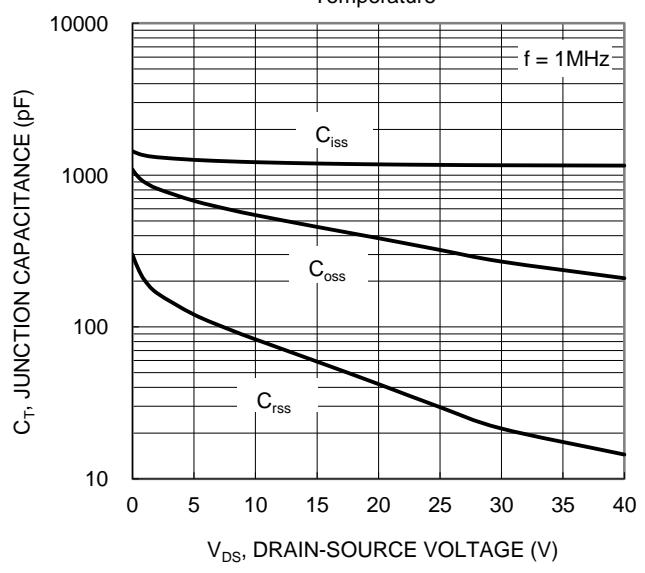
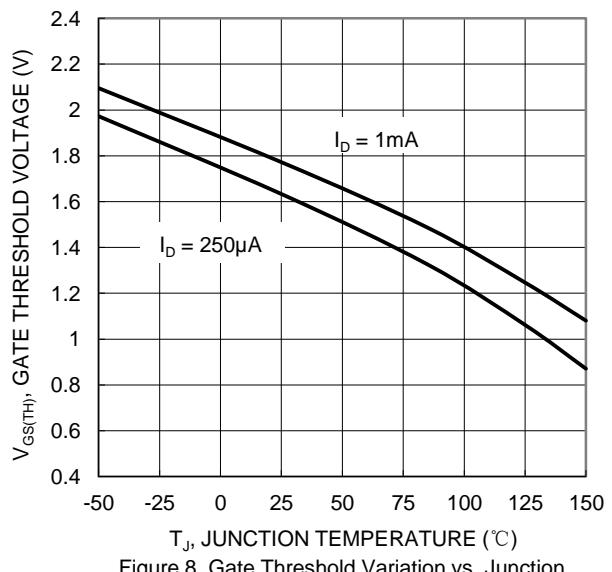
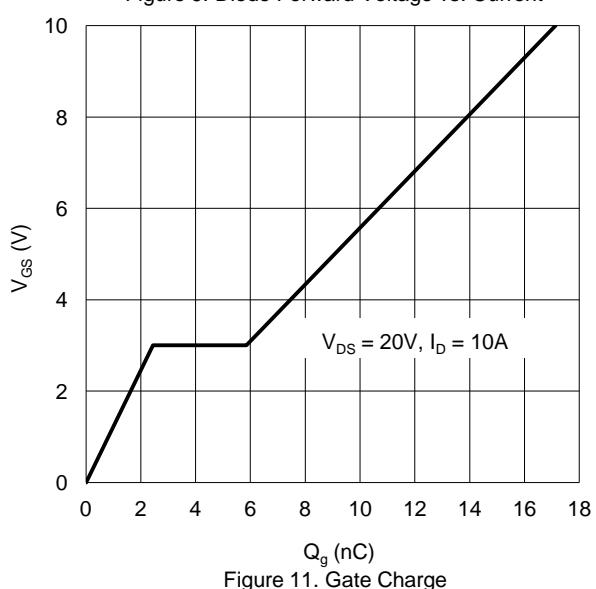
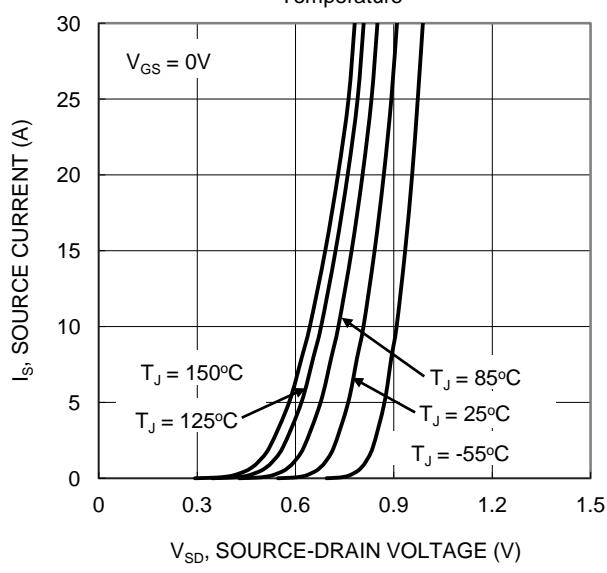
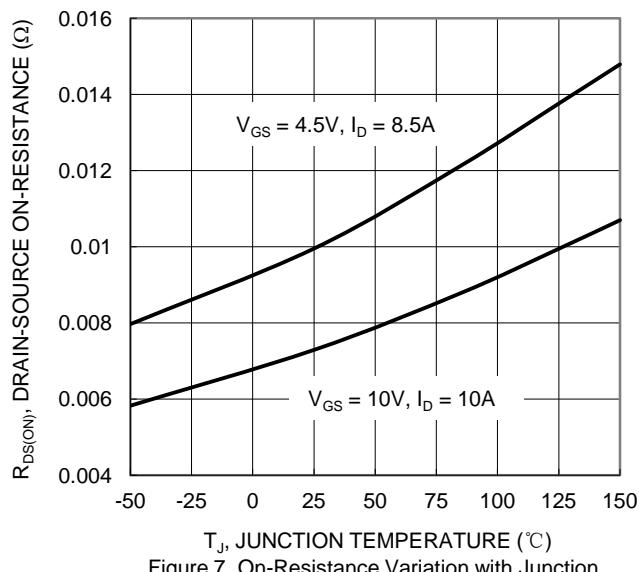


Figure 6. On-Resistance Variation with Junction Temperature



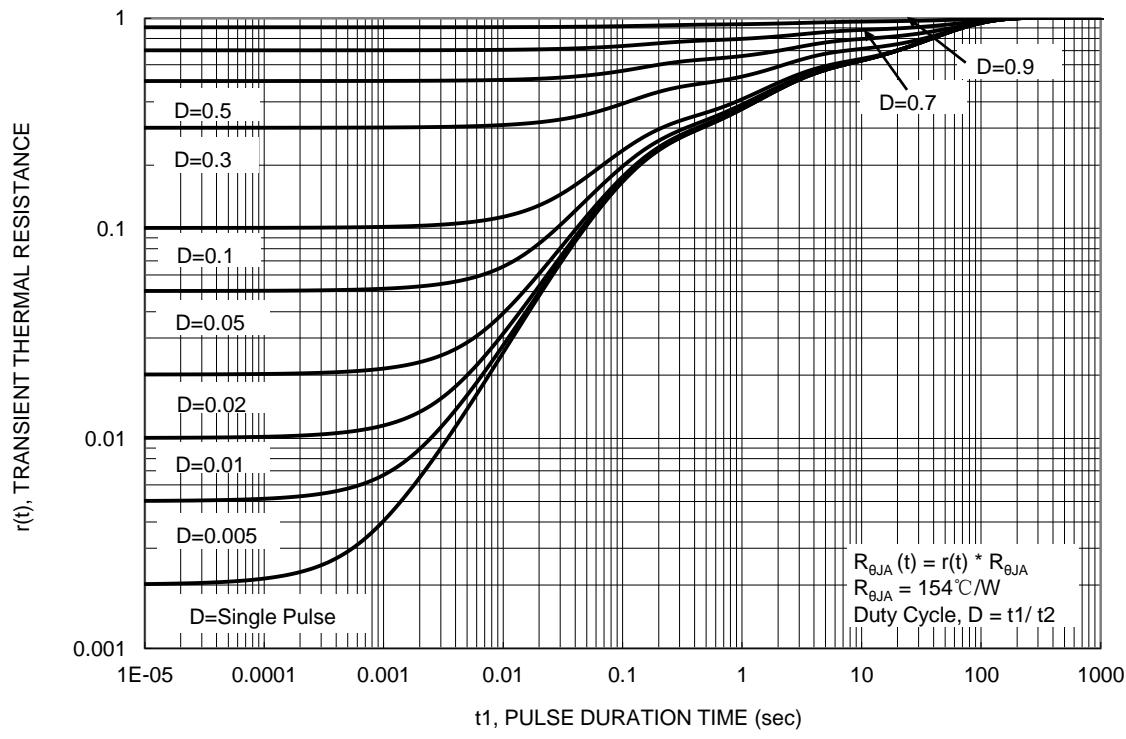
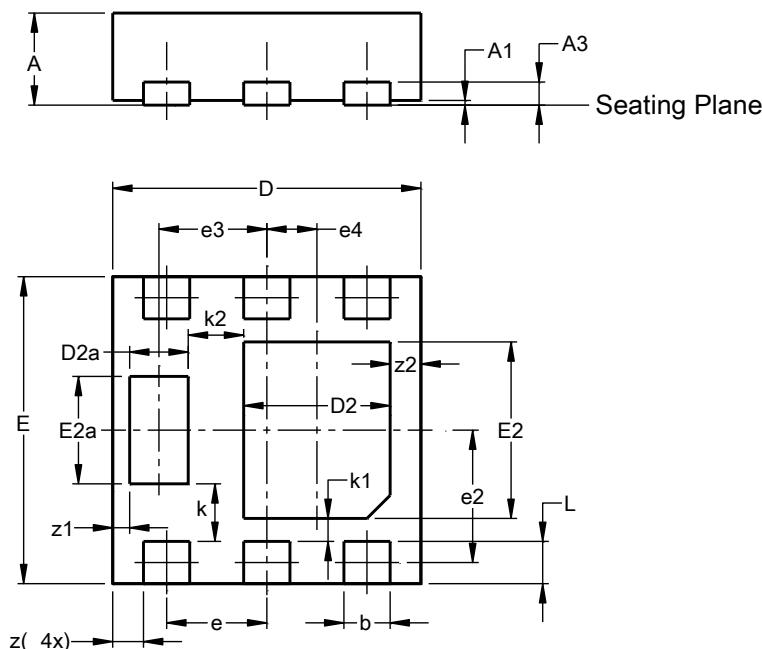


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-6 (Type F)

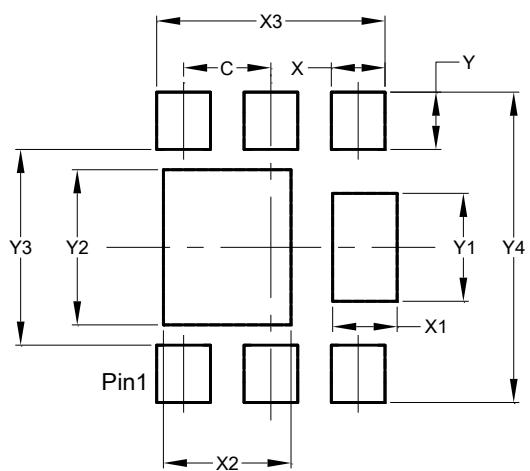


U-DFN2020-6 (Type F)			
Dim	Min	Max	Typ
A	0.57	0.63	0.60
A1	0.00	0.05	0.03
A3	-	-	0.15
b	0.25	0.35	0.30
D	1.95	2.05	2.00
D2	0.85	1.05	0.95
D2a	0.33	0.43	0.38
E	1.95	2.05	2.00
E2	1.05	1.25	1.15
E2a	0.65	0.75	0.70
e	0.65	BSC	
e2	0.863	BSC	
e3	0.70	BSC	
e4	0.325	BSC	
k	0.37	BSC	
k1	0.15	BSC	
k2	0.36	BSC	
L	0.225	0.325	0.275
z	0.20	BSC	
z1	0.110	BSC	
z2	0.20	BSC	
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-6 (Type F)



Dimensions	Value (in mm)
C	0.650
X	0.400
X1	0.480
X2	0.950
X3	1.700
Y	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300

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